# **GSM3117S** 30V P-Channel MOSFETs

#### **Product Description**

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

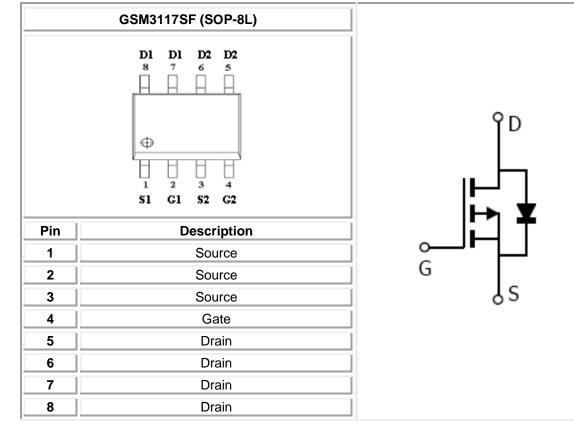
#### **Features**

- -30V, -13.8A, R<sub>DS(ON)</sub><18mΩ@V<sub>GS</sub>=-10V
- Fast switching
- Suit for -4.5V Gate Drive Applications
- Green Device Available
- SOP-8 package design

#### **Applications**

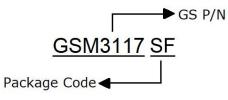
- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

#### Packages & Pin Assignments



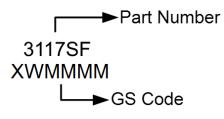


**Ordering Information** 



Part Number	Package	Quantity Reel
GSM3117SF	SOP-8	4000 PCS

## **Marking Information**



#### **Absolute Maximum Ratings**

Tc=25°C Unless otherwise noted

Symbol	Parameter		Typical	Unit	
VDS	Drain-Source Voltage		-30	V	
Vgs	Gate-Source Voltage		±25	V	
	Continuous Drain Current	Tc=25°C	-13.8		
lо		T <sub>C</sub> =70°C	-11.1	Ξ.	
		T <sub>A</sub> =25°C	-7.8	A	
		T <sub>A</sub> =70°C	-6.2		
IDM	Pulsed Drain Current		-50	A	
	Power Dissipation	Tc=25°C	5.3		
PD		T <sub>c</sub> =70°C	3.4		
		T <sub>A</sub> =25°C	1.7	W	
		T <sub>A</sub> =70°C	1.1		
TJ	Operating Junction Temperature Range		-55 to +150	°C	
Tstg	Storage Temperature Range		-55 to +150	°C	
$R_{ extsf{ heta}JA}$	Thermal Resistance-Junction to Ambient		75	°C/W	
$R_{ extsf{ heta}JC}$	Thermal Resistance-Junction to Case		24	°C/W	

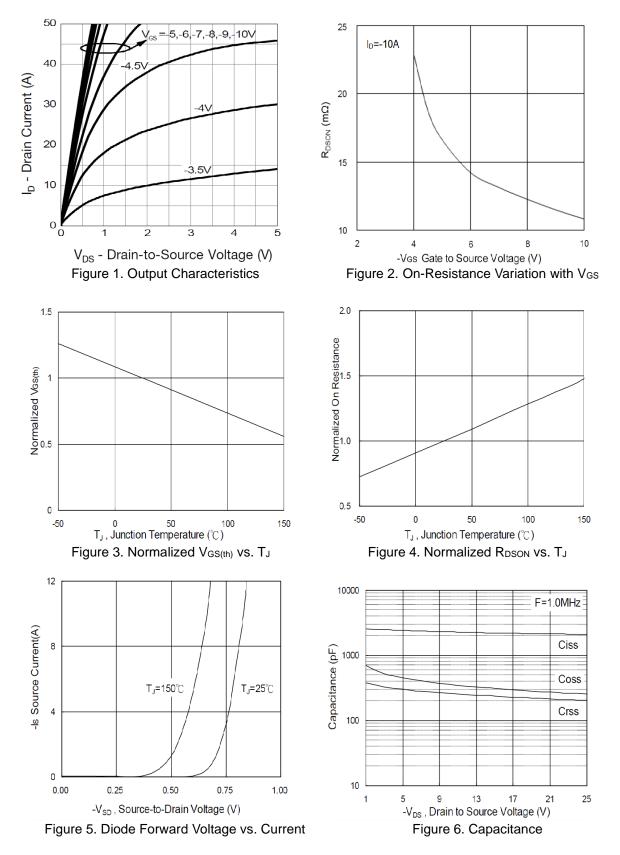


# Electrical Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
	Static	characteristics					
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V, I <sub>D</sub> =-250uA	-30			V	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_{D}=-250uA$	-1.2		-2.5	V	
I <sub>GSS</sub>	Gate Leakage Current	$V_{DS}=0V$ , $V_{GS}=\pm25V$			±100	nA	
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V			-1	uA	
$V_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A			-1	V	
R <sub>DS(on)</sub>		V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A		12.3	18		
	Drain-Source On-Resistance <sup>3</sup>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-6A	19.		26	mΩ	
	Gate cha	rge characteristics					
Qg	Total Gate Charge <sup>3,4</sup>			22		nC	
Q <sub>gs</sub>	Gate-Source Charge <sup>3,4</sup>	V <sub>DD</sub> =-15V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-15A		8.7			
Q <sub>gd</sub>	Gate-Drain Charge <sup>3,4</sup>			7.2			
	Dynam	ic characteristics					
Ciss	Input Capacitance			2215		pF	
Coss	Output Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1.0MHz		310			
Crss	Reverse Transfer Capacitance	1=1.00012		237			
t <sub>d(on)</sub>	Turn-On Time			8			
tr	Rise Time	V <sub>DD</sub> =-15V, V <sub>GS</sub> =-10V,		73.7		ns	
t <sub>d(off)</sub>	Turn-Off Time	Rg=3.3Ω, I <sub>D</sub> =-15A		61.8			
t <sub>f</sub>	Fall Time			24.4			



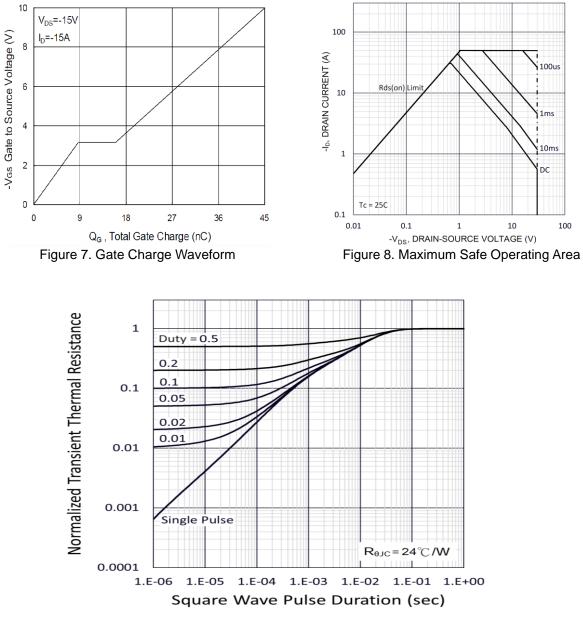




GSM3117SF

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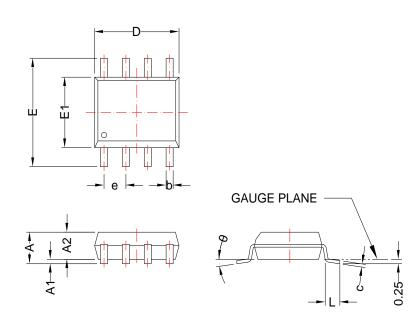
#### **Typical Performance Characteristics (Continue)**

Figure 9. Normalized Transient Thermal Resistance



### **Package Dimension**

SOP-8



DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER END. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE.

	Dimensions				
	Milli	meters	Inc	hes	
SYMBOL	MIN	MAX	MIN	MAX	
Α	1.35	1.75	0.053	0.069	
A1	0.10	0.25	0.004	0.010	
A2	1.25		0.049		
b	0.31	0.51	0.012	0.020	
С	0.10	0.26	0.004	0.010	
D	4.70	5.10	0.185	0.201	
E	5.80	6.20	0.228	0.244	
E1	3.70	4.10	0.146	0.161	
е	1.27 BSC		0.050	BSC	
L	0.4	1.27	0.016	0.050	
θ	0°	8°	0°	8°	



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